

Material Content Data Sheet

RoHS

Sales Product Name	IPD65R950CFD	**Issued**	13. March 2021
MA#	MA001091792		
Package	PG-TO252-3-341	**Weight***	381.82 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.509	0.66	0.66	6572	6572
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		180	
	non noble metal	iron	7439-89-6	0.229	0.06		600	
	non noble metal	copper	7440-50-8	228.946	59.97	60.05	599614	600394
wire	non noble metal	aluminium	7429-90-5	0.426	0.11	0.11	1114	1114
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.731	0.45		4535	
	plastics	brominated resin	-	1.855	0.49		4859	
	organic material	carbon black	1333-86-4	1.979	0.52		5182	
	plastics	epoxy resin	-	16.696	4.37		43727	
	inorganic material	silicondioxide	60676-86-0	101.412	26.56	32.39	265599	323902
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9795	9795
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1333	1333
solder	non noble metal	tin	7440-31-5	0.050	0.01		132	
	noble metal	silver	7440-22-4	0.063	0.02		165	
	non noble metal	lead	7439-92-1	2.406	0.63	0.66	6302	6599
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019			50	
	non noble metal	copper	7440-50-8	19.177	5.02	5.02	50226	50291
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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